Plasma-polymer interactions: A review of progress in u durability during plasma etching for nanoscale fabricat

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Citation Report

#	Article	IF	Citations
1	Ion and Vacuum Ultraviolet Photon Beam Effects in 193â€‰nm Photoresist Surface Roughening: The Role of the Adamantyl Pendant Group. Plasma Processes and Polymers, 2011, 8, 1068-1079.	1.6	18
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4	Characterization and mechanism of He plasma pretreatment of nanoscale polymer masks for improved pattern transfer fidelity. Applied Physics Letters, 2011, 99, 261501.	1.5	10
5	On the absence of post-plasma etch surface and line edge roughness in vinylpyridine resists. Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics, 2011, 29, .	0.6	21
6	Real-time measurements of plasma photoresist modifications: The role of plasma vacuum ultraviolet radiation and ions. Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics, 2012, 30, .	0.6	18
7	Direct and quantitative evidence for buckling instability as a mechanism for roughening of polymer during plasma etching. Applied Physics Letters, 2012, 100, .	1.5	10
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9	Ion contributions to gasâ€“surface interactions in inductively-coupled fluorocarbon plasmas. International Journal of Mass Spectrometry, 2012, 330-332, 46-57.	0.7	6
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